

1 Characteristics

Table 2: Absolute ratings (limiting values at 25 °C, unless otherwise specified, anode terminals short-circuited)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive peak reverse voltage		50	V
$I_{F(RMS)}$	Forward rms current		25	A
$I_{F(AV)}$	Average forward current $\delta = 0.5$, square wave	$T_C = 130\text{ °C}$	15	A
I_{FSM}	Surge non repetitive forward current	$t_p = 10\text{ ms sinusoidal}$	100	A
T_{stg}	Storage temperature range		-65 to +175	°C
T_j	Maximum operating junction temperature ⁽¹⁾		150	°C

Notes:

⁽¹⁾ $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 3: Thermal resistance parameters

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	1.4	°C/W

Table 4: Static electrical characteristics (anode terminals short circuited)

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = 35\text{ V}$	-		470	μA
		$T_j = 125\text{ °C}$		-	16	32	mA
		$T_j = 25\text{ °C}$	$V_R = V_{RRM}$	-	250	650	μA
		$T_j = 125\text{ °C}$		-	20	40	mA
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 5\text{ A}$	-	0.36		V
		$T_j = 125\text{ °C}$		-	0.31	0.36	
		$T_j = 25\text{ °C}$	$I_F = 10\text{ A}$	-	0.43	0.48	
		$T_j = 125\text{ °C}$		-	0.42	0.46	
		$T_j = 25\text{ °C}$	$I_F = 15\text{ A}$	-	0.49		
		$T_j = 125\text{ °C}$		-	0.49	0.55	

Notes:

⁽¹⁾Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$

⁽²⁾Pulse test: $t_p = 380\text{ μs}$, $\delta < 2\%$

To evaluate the maximum conduction losses use the following equation:

$$P = 0.25 \times I_{F(AV)} + 0.02 \times I_{F(RMS)}^2$$

1.1 Characteristics (curves)

Figure 1: Average forward power dissipation versus average forward current

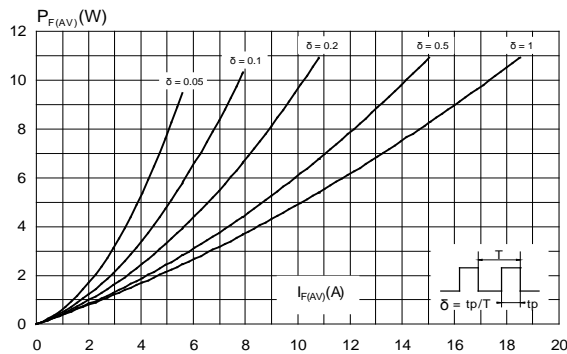


Figure 2: Average forward current versus ambient temperature ($\delta = 0.5$)

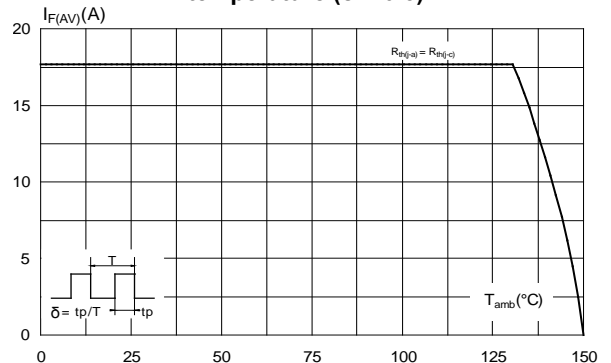


Figure 3: Relative variation of thermal impedance junction to case versus pulse duration

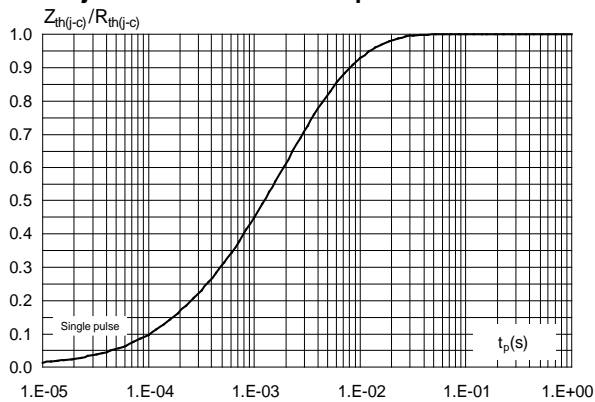


Figure 4: Reverse leakage current versus reverse voltage applied (typical values)

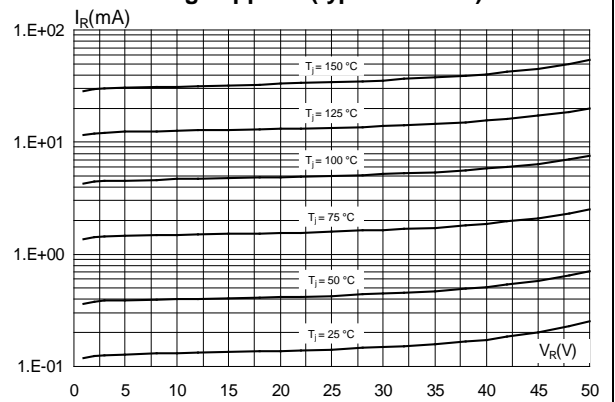


Figure 5: Junction capacitance versus reverse voltage applied (typical values)

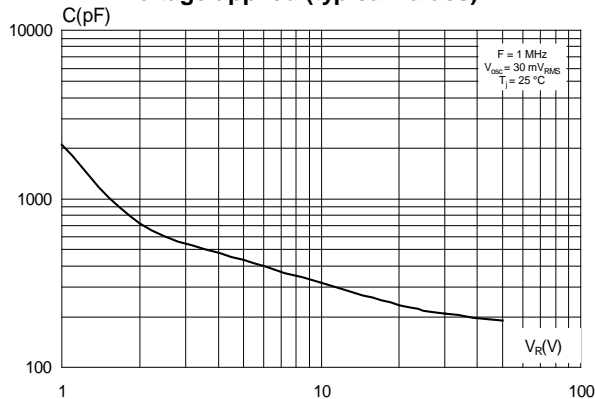


Figure 6: Forward voltage drop versus forward current (typical values)

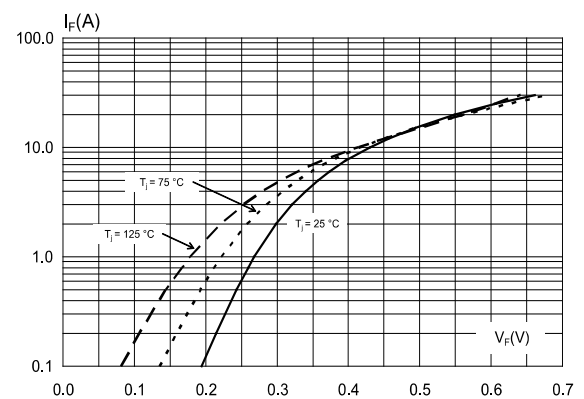
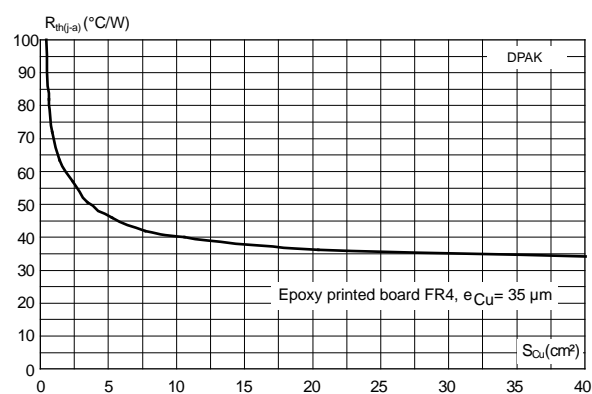


Figure 7: Thermal resistance junction to ambient versus copper surface under tab for DPAK (typical values)



2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

- Cooling method: by conduction (C)
- Epoxy meets UL 94,V0

2.1 DPAK package information

Figure 8: DPAK package outline

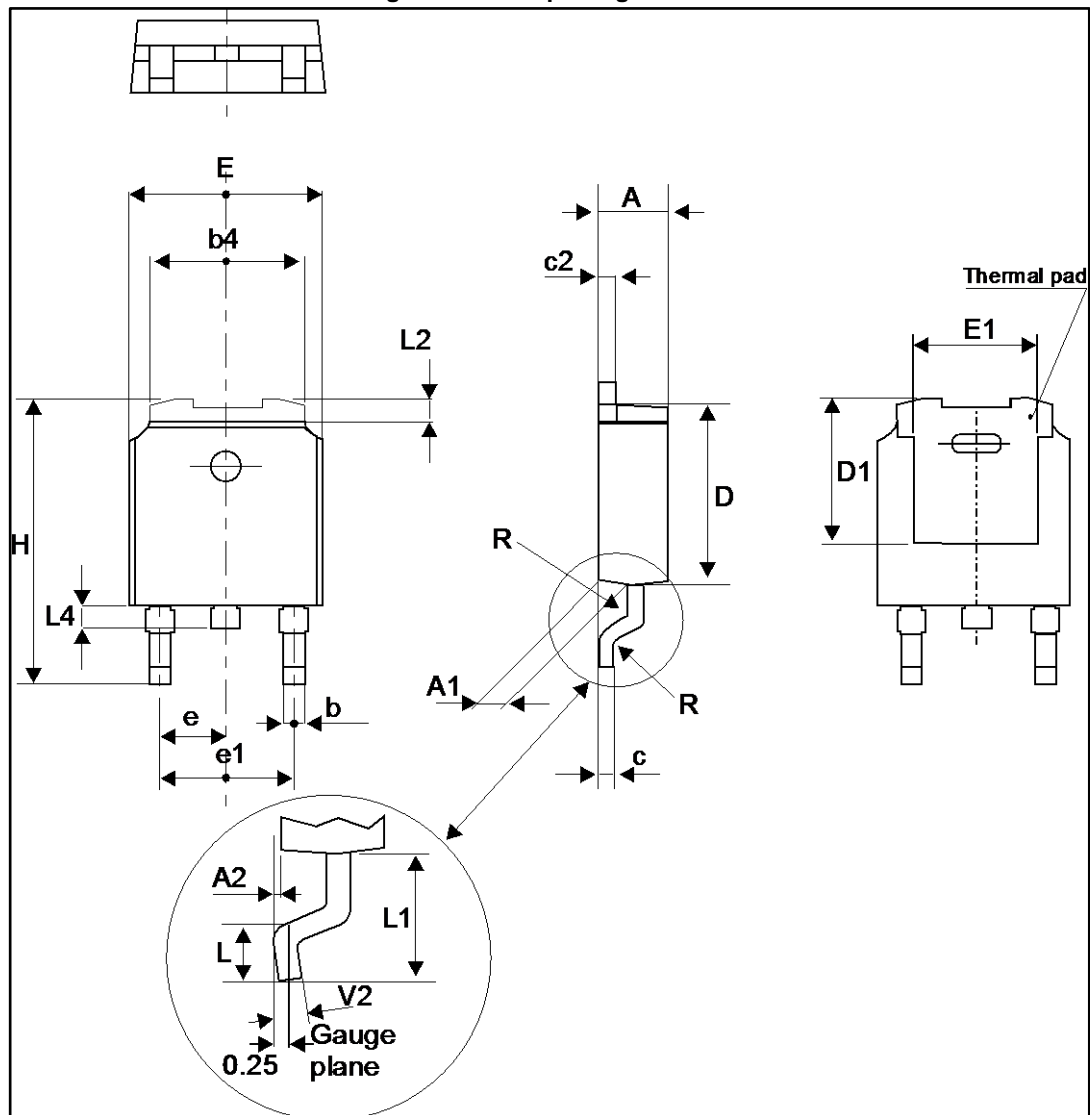
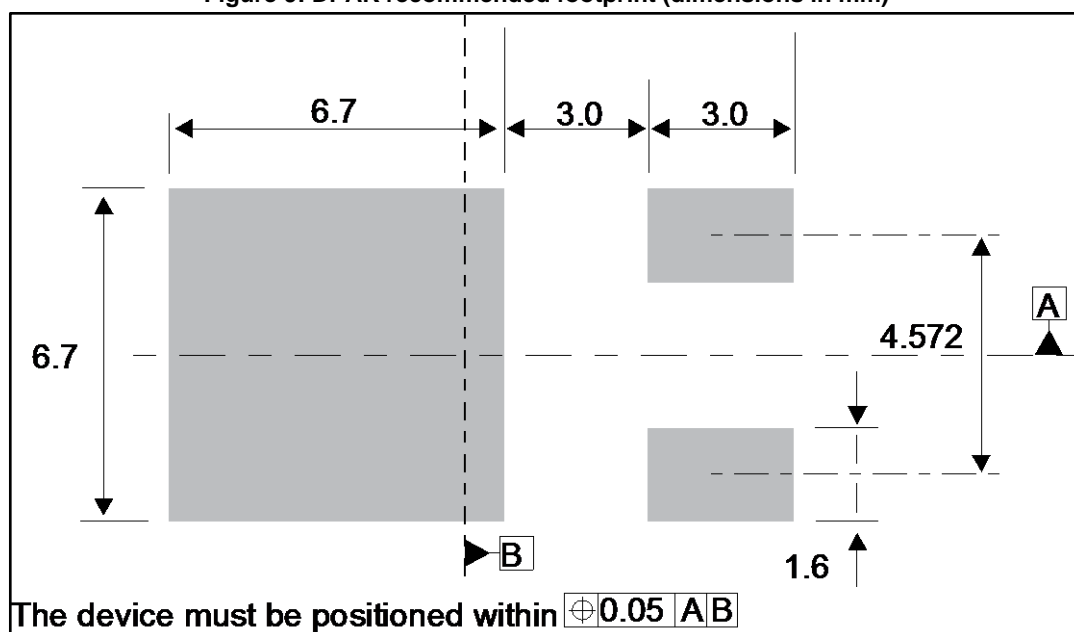


Table 5: DPAK package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.18	2.40	0.085	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
b	0.64	0.90	0.025	0.035
b4	4.95	5.46	0.194	0.215
c	0.46	0.61	0.018	0.024
c2	0.46	0.60	0.018	0.023
D	5.97	6.22	0.235	0.244
D1	4.95	5.60	0.194	0.220
E	6.35	6.73	0.250	0.265
E1	4.32	5.50	0.170	0.216
e	2.286 typ.		0.090 typ.	
e1	4.40	4.70	0.173	0.185
H	9.35	10.40	0.368	0.409
L	1.0	1.78	0.039	0.070
L2		1.27		0.050
L4	0.60	1.02	0.023	0.040
V2	-8°	+8°	-8°	+8°

Figure 9: DPAK recommended footprint (dimensions in mm)



3 Ordering information

Table 6: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
FERD15S50SB-TR	FERD 15S50	DPAK	0.32 g	2500	Tape and reel

4 Revision history

Table 7: Document revision history

Date	Revision	Changes
09-Feb-2017	1	Initial release.

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